

The international forum where the high-performance computing and high-speed networking communities meet

Join us at Huawei North America Headquarters for Hot Interconnects 2012!

Hot Interconnects is the premier international forum for researchers and developers of state-of-the-art hardware and software architectures and implementations for interconnection networks of all scales, ranging from multi-core on-chip interconnects to those within systems, clusters, data centers, and cloud facilities. This yearly conference is attended by leaders in industry and academia. The atmosphere provides for a wealth of opportunities to interact with individuals at the forefront of this field.

Themes include cross-cutting issues spanning computer systems, networking technologies, and communication protocols for high-performance interconnection networks. This conference is directed particularly at new and exciting technology and product innovations in these areas. Contributions should focus on real experimental systems, prototypes, or leading-edge products and their performance evaluation. In addition to those subscribing to the main theme of the conference, contributions are also solicited in the topics listed below.

Building on last year's successful technical program, keynotes, sessions, and panels on datacenter networking and their requirements, and solutions, the 2012 edition of Hot Interconnects takes place at the Huawei North America, Santa Clara, CA. The focal point of this year's conference revolves around challenges and techniques for "Big Data networking". We hope you can join us there.

CALL FOR PAPERS

TOPICS

- Novel and innovative interconnect architectures
- Multi-core processor interconnects
- System-on-Chip Interconnects
- Advanced chip-to-chip communication technologies
- Optical interconnects
- Protocols and interfaces for inter-processor communication
- Survivability and fault-tolerance of interconnects
- High-speed packet processing engines and network processors
- System and storage area network architectures and protocols
- High-performance host-network interface architectures
- High-bandwidth and low-latency I/O
- Tb/s or Pb/s switching and routing technologies
- Innovative architectures for supporting collective communication
- Novel communication architectures to support grid computing
- Centralized and distributed cloud interconnects
- Requirements driving high-performance interconnects
- Traffic characterization for HPC systems and commercial data Centers
- Software for Network/Fabric Bring-up, Configuration and Performance Management, e.g., OpenFlow or OpenSM

SUBMISSION GUIDELINES

Submission deadline: May 20, 2012 (extended)
Author notification: June 16, 2012

- Papers need sufficient technical detail to judge quality and suitability for presentation.
- Paper limit: eight pages, two columns
- Submit title, author, abstract, and full paper (eight pages, double-column, IEEE format)
- Papers should be submitted electronically at the specified link location found on <http://www.hoti.org>
- For further information please see <http://www.hoti.org>

ABOUT THE CONFERENCE

- Conference held on August 22-23, 2012 at Huawei North America Headquarters, Santa Clara, CA
- Papers selected will be published in proceedings by the IEEE Computer Society
- Presentations are 30-minute talks in a single-track format
- Online information at <http://www.hoti.org>

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